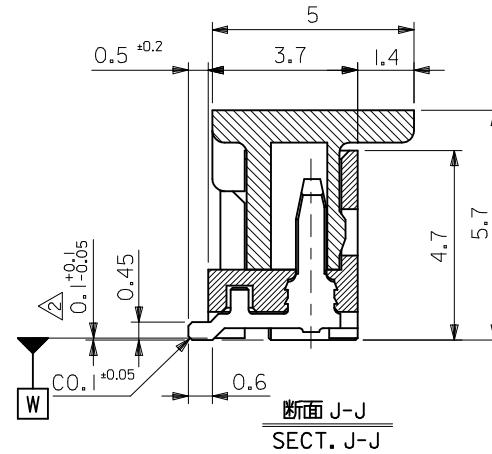


**NOTES**

1. 嵌合相手: 51021シリーズ MATE WITH : 51021 SERIES
2. 水平面上においての、ウエハー底面 **W** とソルダーテール及びフィッティングネイル底面とのズレ量を示す。  
MISALIGNMENT OF SOLDER TAIL & FITTING NAIL FROM **W**
3. 偶数極のみ適用。APPLY EVEN CIRCUIT PRODUCTS.
4. 本製品は 53398-\*\*\*20 の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 53398-\*\*\*20.

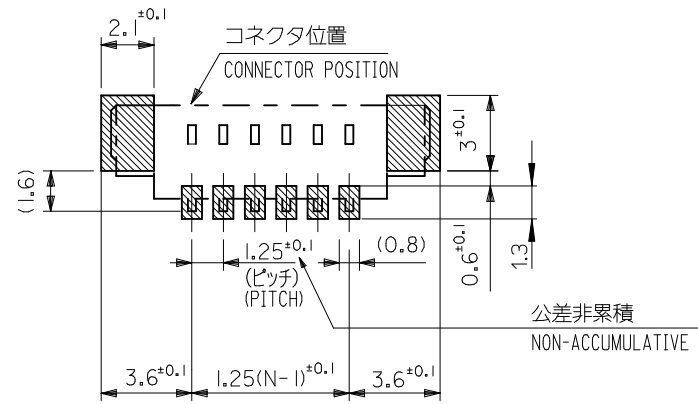


17.35	18.05	19.25	20	22.25	16.25	22.3	53398-1429	14
14.85	15.55	16.75	17.5	19.75	13.75	20.15	53398-1229	12
9.85	10.55	11.75	12.5	14.75	8.75	15.15	53398-0829	8
8.6	9.3	10.5	11.25	13.5	7.5	13.9	53398-0729	7
7.35	8.05	9.25	10	12.25	6.25	12.65	53398-0629	6
6.1	6.8	8	8.75	11	5	11.4	53398-0529	5
4.85	5.55	6.75	7.5	9.75	3.75	10.15	53398-0429	4
3.6	4.3	5.5	6.25	8.5	2.5	8.9	53398-0329	3
2.35	3.05	4.25	5	7.25	1.25	7.65	53398-0229	2
G	F	E	D	C	B	A	MATERIAL NO.	CIRCUITS

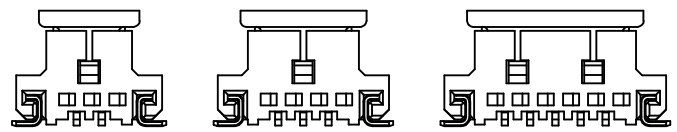
MODEL NO. 53398-\*\*\*29

DISCRIPTION	MATERIAL
① WAFER	46NYLON (30% GLASS FILLED) UL94V-0
② COVER	
③ FITTING NAIL	リン青銅、ニッケル下地 無光沢鍍めつき PHOSPHOR BRONZE, PLATING : MATTE TIN 1.0 μm MIN. UNDERPLATE : NICKEL 1.0 μm MIN.
④ PIN	

REVISED EC NO: J2017-0507 DRWN:SOBARA01 2017/03/31 CHKD: APPR:TKANEKO 2017/04/04	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE <b>MM ONLY</b>		SCALE <b>8:1</b>	DESIGN UNITS <b>METRIC</b>	THIRD ANGLE PROJECTION	
	0.25 UNDER	UNDER	±0.03	DRAWN BY Y. SAKIYAMA	DATE 2004/02/12	TITLE <b>PICOBLADE 1.25 HEADER ASSY WITH COVER SMT ST TYPE</b>		
	0.25 OVER	0.5 UNDER	±0.05	CHECKED BY M. SASAO	DATE 2004/02/12	DOCUMENT NO. <b>SD-53398-034</b>		
	0.5 OVER	1.0 UNDER	±0.1	APPROVED BY M. SASAO	DATE 2004/02/12	SHEET NO. <b>1 OF 2</b>		
1.0 OVER	30 UNDER	±0.2	MATERIAL NO.		SEE CHART			
10 OVER	30 UNDER	±0.25	SIZE <b>A3</b>		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
30 OVER		±0.3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					

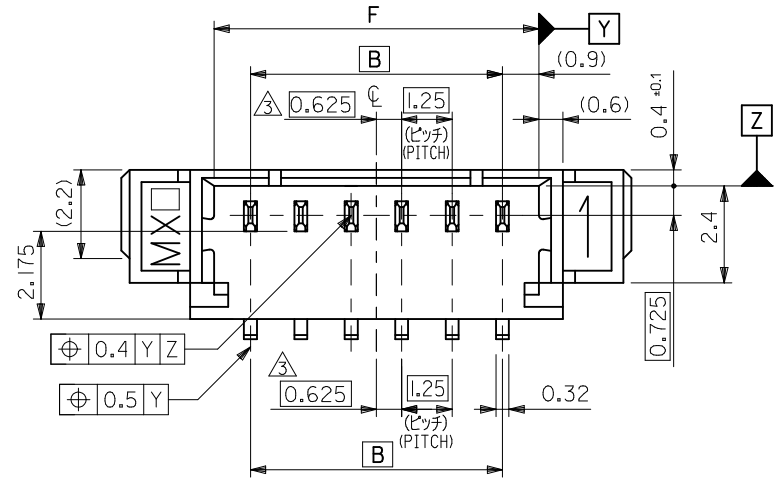


参考基板レイアウト  
RECOMMENDED P.C.BOARD PATTERN DIM.(REF.)



2極 2 CKT.  
3極 3 CKT.  
4極以上 OVER 4 CKT.

△ ロック形状図  
LOCK CONFIGURATION



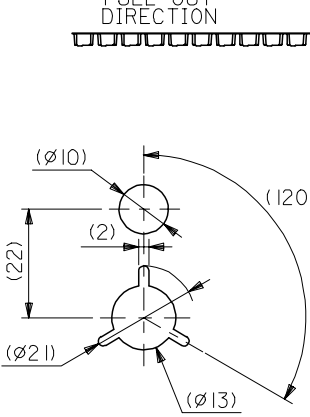
カバーなしの場合 (53398-\*\*\*19)  
IN CASE OF WITHOUT COVER

NOTES

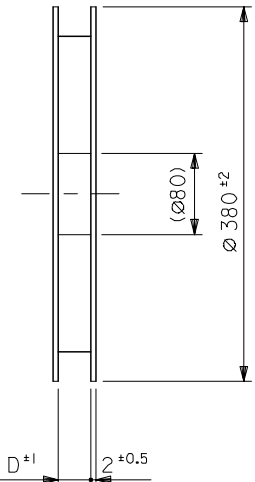
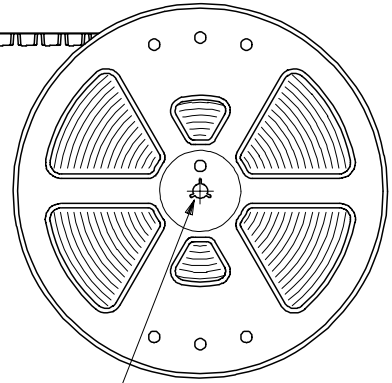
- △ ロック窓は、2、3極は1ヶ所、4極以上は2ヶ所とする。  
LOCKING WINDOW : ONE PLACE FOR 2&3 CKTS.  
TWO PLACES FOR MORE THAN 4 CKTS.
- 6. ソルダータール及び金具の平坦度は0.1以下。  
SOLDER TAIL & FITTING NAIL COPLANARITY TO BE 0.1 MAX.

REVISED EC NO: J2017-0507 DRWN:SOBARA01 2017/03/31 CHKD: APPR:TKANEKO 2017/04/04	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	MODEL NO.
	0.25 UNDER UNDER ±0.03		MM ONLY		8:1	METRIC	53398-***29
	0.25 OVER 0.5 UNDER ±0.05		DRAWN BY DATE		TITLE		
	0.5 OVER 1.0 UNDER ±0.1		Y. SAKIYAMA 2004/02/12		PICOBLADE 1.25 HEADER ASSY WITH COVER SMT ST TYPE		
	1.0 OVER 10 UNDER ±0.2		CHECKED BY DATE				
10 OVER 30 UNDER ±0.25		M. SASAO 2004/02/12					
30 OVER ±0.3		APPROVED BY DATE		MATERIAL NO.		DOCUMENT NO.	SHEET NO.
ANGULAR ±3 °		M. SASAO 2004/02/12		SEE CHART		SD-53398-034	2 OF 2
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
		A3					

引き出し方向  
PULL OUT DIRECTION

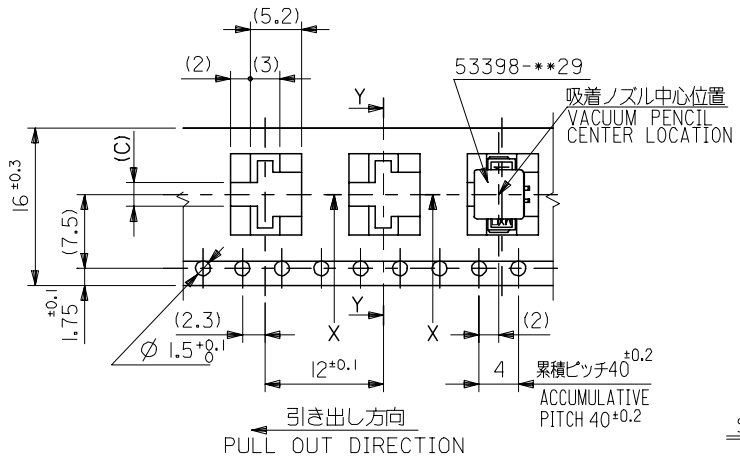
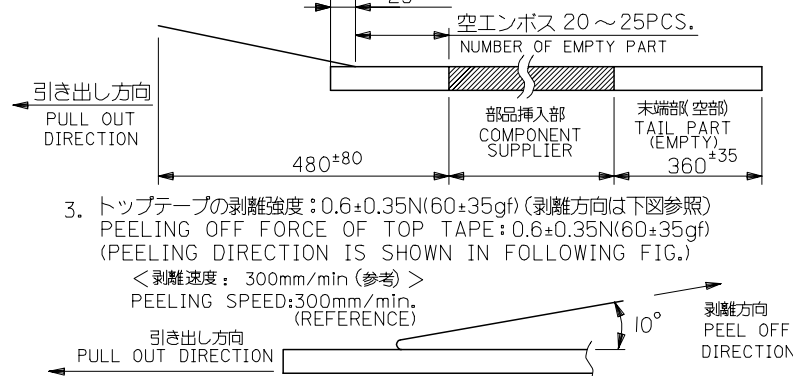


DETAIL "F"



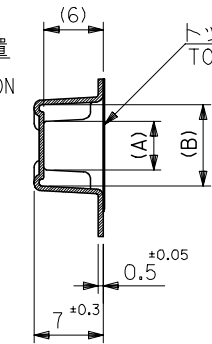
NOTES

- 梱包数量: 1000個/リール  
NUMBER OF CONNECTOR: 1000PCS/REEL
- リードテープ長さ  
LEAD TAPE LENGTH  
トップテープ未接着部  
TOP TAPE NON-BONDED PART  
25±0  
空インボス 20~25PCS.  
NUMBER OF EMPTY PART  
部品挿入部  
COMPONENT SUPPLIER  
末端部(空部)  
TAIL PART (EMPTY)  
360±35  
3. トップテープの剥離強度: 0.6±0.35N(60±35gf) (剥離方向は下図参照)  
PEELING OFF FORCE OF TOP TAPE: 0.6±0.35N(60±35gf)  
(PEELING DIRECTION IS SHOWN IN FOLLOWING FIG.)  
<剥離速度: 300mm/min(参考)>  
PEELING SPEED: 300mm/min. (REFERENCE)  
4. 53398-\*\*\*29の詳細寸法については図面 SD-53398-034 を参照下さい。  
RE DETAILED DIMENSIONS, SEE SD-53398-034.  
5. 材料 (MATERIAL)  
キャリアテープ (CARRIER TAPE): ポリプロピレン (POLYPROPYLENE)  
トップテープ (TOP TAPE): PET, PE, PEF  
リール (REEL): ポリスチレン (PS) <リサイクル材含む>  
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>  
6. 本製品は 53398-\*\*\*80 の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 53398-\*\*\*80.

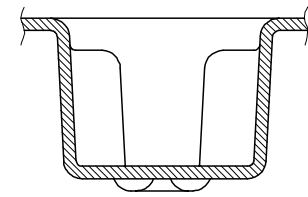


引き出し方向  
PULL OUT DIRECTION

16幅テープ  
(TAPE WIDTH: 16)



SECT: Y-Y



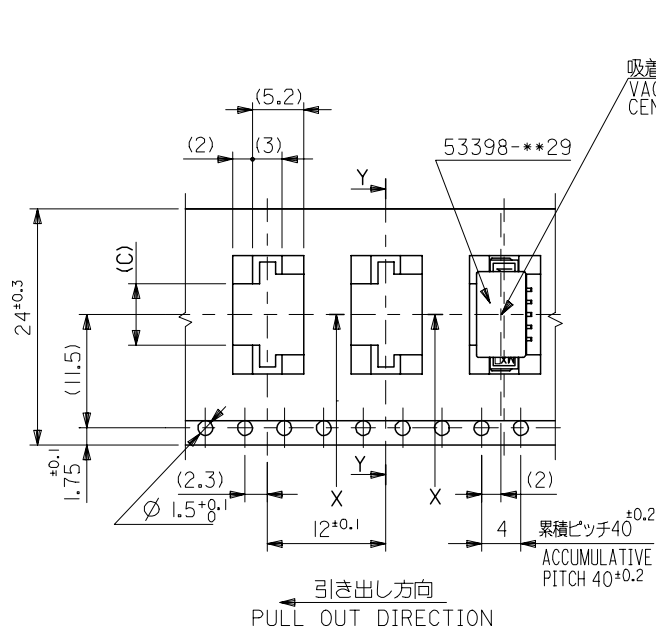
SECT: X-X

32	33.4	14.95	20.75	17.05	53398-1267	12
24	25.4	9.95	15.75	12.05	53398-0867	8
		8.7	14.5	10.8	53398-0767	7
		7.45	13.25	9.55	53398-0667	6
		6.2	12	8.3	53398-0567	5
		4.95	10.75	7.05	53398-0467	4
3.7	9.5	5.8	53398-0367	3		
16	17.4	2.45	8.25	4.55	53398-0267	2
キャリアテープ幅 CARRIER TAPE WIDTH	D	(C)	(B)	(A)	MATERIAL NO.	CIRCUITS

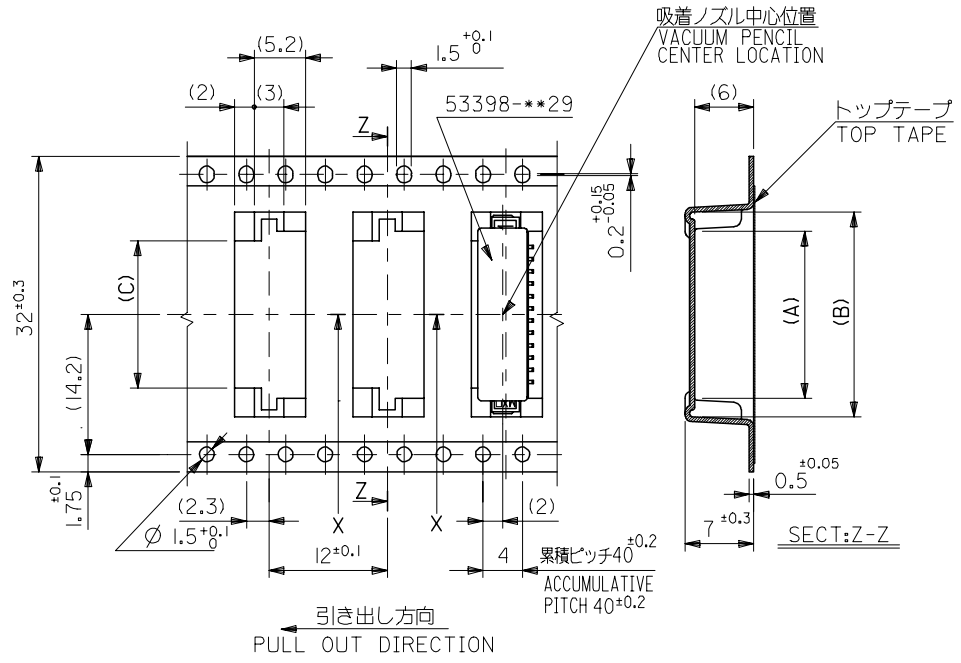
REVISED EC NO: DRAWN: MERICUCH CHK: K. ASAKAWA APP: R. SICHIKAWA 2004/07/28 2004/07/28 2004/07/30	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY J. SASAMO	DATE 2004/7/22	TITLE EMBSTP PKG FOR 1.25 W/B CONN. WAFER ASSY -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE 2004/7/22	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY N. UKITA	DATE 2004/7/22	DOCUMENT NO. SD-53398-035	SHEET NO. 1 OF 2	
	ANGULAR	±3 °	MATERIAL NO. SEE CHART				
A	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

10 9 8 7 6 5 4 3 2 1

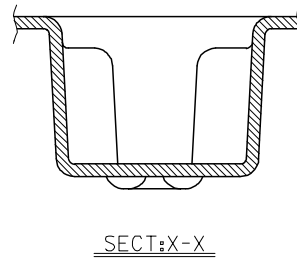
F  
E  
D  
C  
B  
A



24幅テープ  
(TAPE WIDTH:24)



32幅テープ  
(TAPE WIDTH:32)



SECT:X-X

REVISED EC NO: 2004/07/28 DRAWN: M. I. GUCH CHK'D: K. ASAKAW APPR: S. ICHIKAW 2004/07/28 2004/07/30	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY J. SASAMO	DATE 2004/7/22	TITLE EMBSTP PKG FOR 1.25 W/B CONN. WAFER ASSY -LEAD FREE-	
	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE 2004/7/22	MOLEX INCORPORATED	
	30 OVER	±0.3	APPROVED BY N. UKITA	DATE 2004/7/22	DOCUMENT NO. SD-53398-035	SHEET NO. 2 OF 2
	ANGULAR	±3 °	MATERIAL NO. SEE CHART			
A	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			